

Title (en)

DEVICE AND METHOD FOR FORMING A DEVICE HAVING A CAVITY WITH CONTROLLED ATMOSPHERE

Title (de)

VORRICHTUNG MIT KAVITÄT KONTROLLIERTER ATMOSPHERE UND IHRE HERSTELLUNG

Title (fr)

DISPOSITIF ET PROCEDE DE FORMATION D'UN DISPOSITIF PRESENTANT UNE CAVITE A ATMOSPHERE CONTROLEE

Publication

**EP 1090419 A1 20010411 (FR)**

Application

**EP 99925122 A 19990617**

Priority

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- FR 9807841 A 19980622

Abstract (en)

[origin: FR2780200A1] The system uses two rings of material - one to seal and one to adhere components.- DETAILED DESCRIPTION - The device comprises a support plate (100) and at least one cover (104) capable of being sealed to the support to form with it a cavity (114). This provides a controlled atmosphere around a component (102). Either the cover or the support is provided with a wedge (110) made of fusible material, and a seal bead (112) formed around the component. Prior to being sealed, the fusible material wedge is of sufficient thickness to prevent the seal bead from coming into contact with the second component (cover or support) when these two parts are assembled. The components are heated within a controlled environment, with the required atmospheric conditions, rising to a temperature at which the fusible material melts to adhere the components

IPC 1-7

**H01L 21/50**; H01L 23/10

IPC 8 full level

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